N-Channel 30-V (D-S) 175°C MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)[b]
30	0.0065 @ V_{GS} = 10 V	84[b]
	0.0095 @ V_{GS} = 4.5 V	59[b]

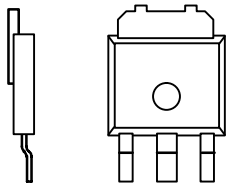
FEATURES

- TrenchFET® Power MOSFET
- 175°C Junction Temperature
- Optimized for Low-Side Synchronous Rectifier Operation
- 100% R_g Tested

APPLICATIONS

- DC/DC Converters
  - Desktop CPU Core
- Synchronous Rectifiers

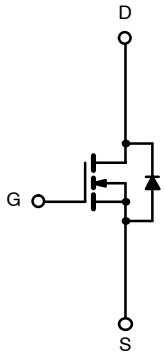
TO-252
Reverse Lead DPAK



Drain Connected to Tab

Top View

Ordering Information:
SUR50N03-06P—E3
SUR50N03-06P-T4—E3 (altrenate tape orientation)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_A = 25°C	I_D	27	A
	T_C = 25°C		84[b]	
	T_C = 100°C		59[b]	
Pulsed Drain Current		I_{DM}	100	
Continuous Source Current (Diode Conduction)[a]		I_S	25	
Maximum Power Dissipation	T_C = 25°C	P_D	88	W
	T_A = 25°C		8.3[a]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	–55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[a]	t ≤ 10 sec	R_{thJA}	15	18	°C/W
	Steady State		40	50	
Maximum Junction-to-Case		R_{thJC}	1.4	1.7	

Notes
a. Surface Mounted on FR4 Board, t ≤ 10 sec.
b. Based on maximum allowable junction temperature, package limitation current is 50 A.

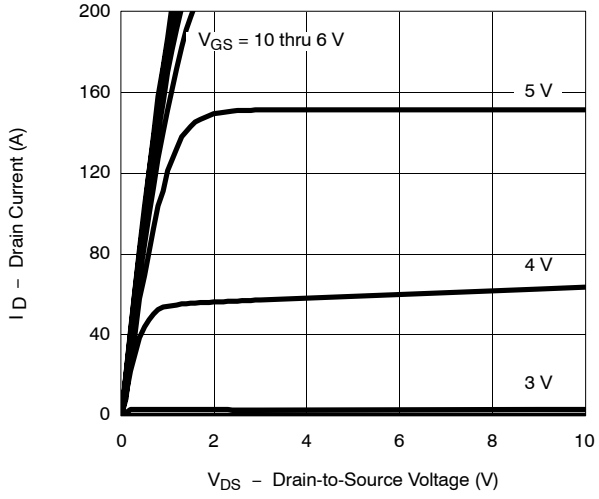
SPECIFICATIONS (T_J = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ[a]	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	1.0		3.0	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V			1	μA
		V_{DS} = 30 V, V_{GS} = 0 V, T_J = 125°C			50	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	50			A
Drain-Source On-State Resistance[b]	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 20 A		0.0053	0.0065	Ω
		V_{GS} = 10 V, I_D = 20 A, T_J = 125°C			0.0105	
		V_{GS} = 4.5 V, I_D = 20 A		0.0078	0.0095	
Forward Transconductance[b]	g_{fs}	V_{DS} = 15 V, I_D = 20 A	20			S
Dynamic[a]						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		3100		pF
Output Capacitance	C_{oss}			565		
Reverse Transfer Capacitance	C_{rss}			255		
Gate Resistance	R_g		1	1.9	3.1	Ω
Total Gate Charge[c]	Q_g	V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 50 A		21	30	nC
Gate-Source Charge[c]	Q_{gs}			10		
Gate-Drain Charge[c]	Q_{gd}			7.5		
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = 15 V, R_L = 0.3 Ω I_D ≅ 50 A, V_{GEN} = 10 V, R_g = 2.5 Ω		12	20	ns
Rise Time[c]	t_r			12	20	
Turn-Off Delay Time[c]	$t_{d(off)}$			30	45	
Fall Time[c]	t_f			10	15	
Source-Drain Diode Ratings and Characteristic (T_C = 25°C)						
Pulsed Current	I_{SM}				100	A
Diode Forward Voltage[b]	V_{SD}	I_F = 100 A, V_{GS} = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t_{rr}	I_F = 50 A, di/dt = 100 A/μs		35	70	ns

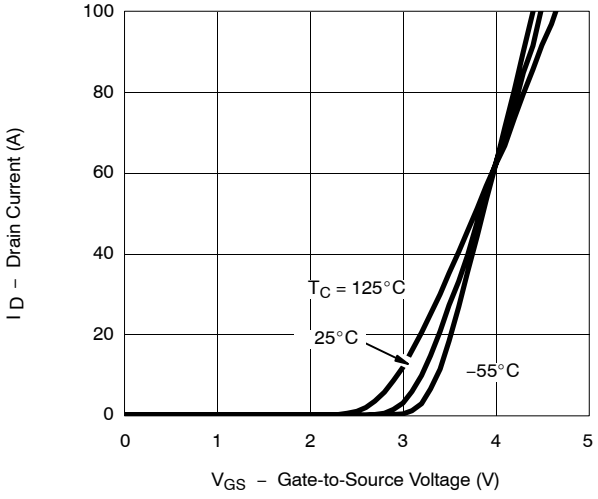
Notes
a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
c. Independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

Output Characteristics

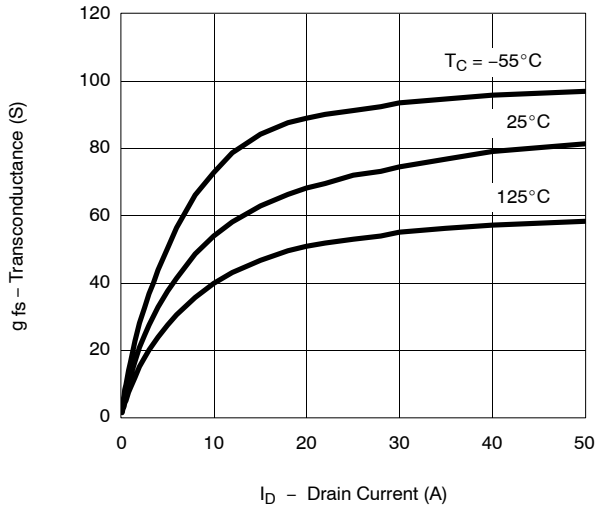


Transfer Characteristics

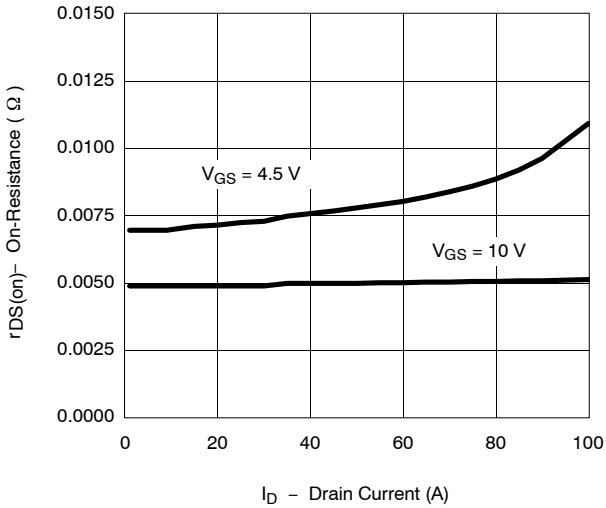


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

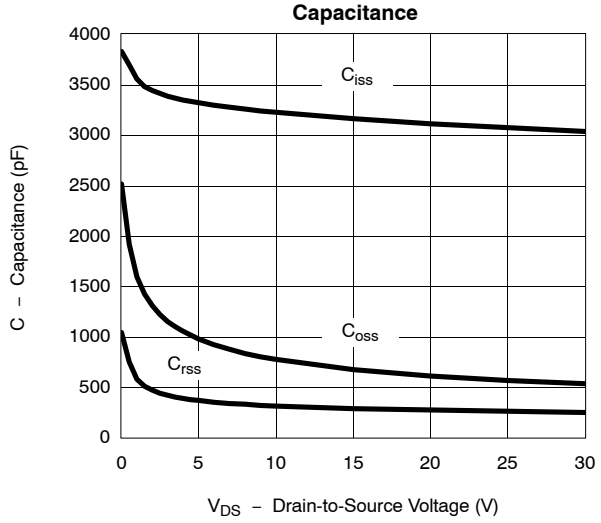
Transconductance



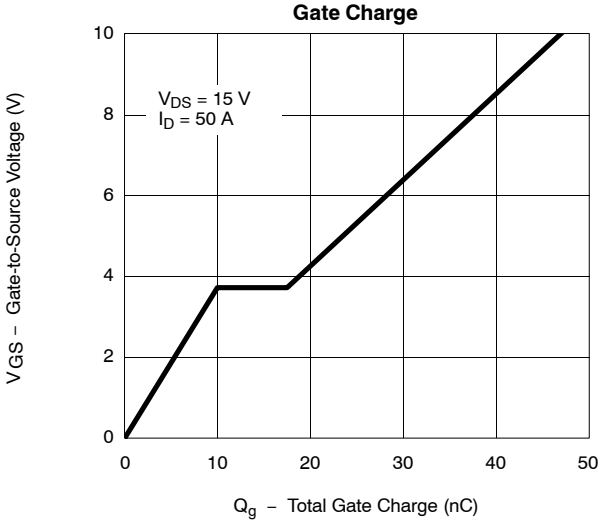
On-Resistance vs. Drain Current



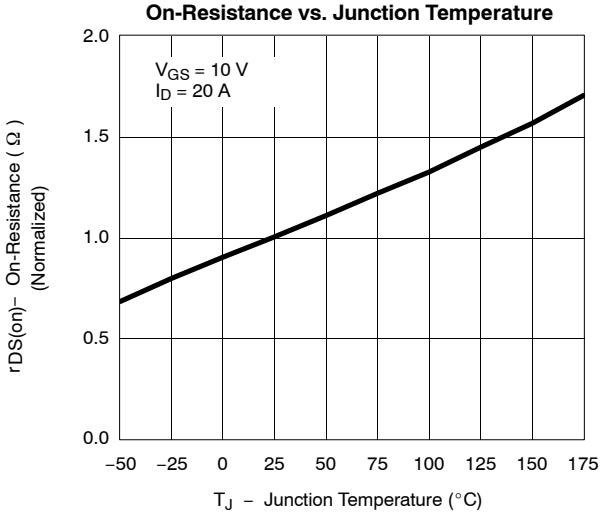
Capacitance



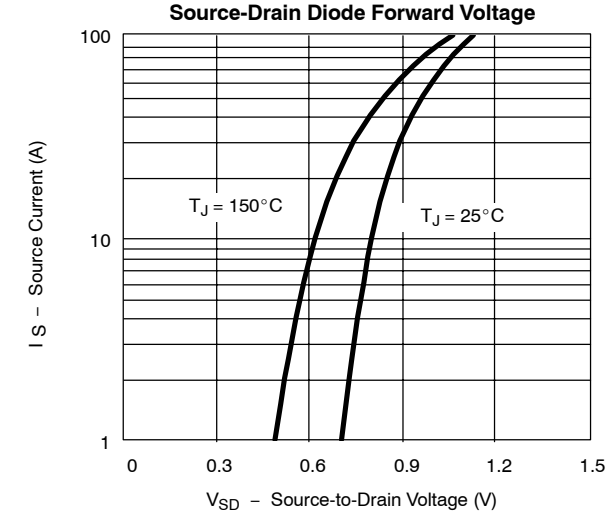
Gate Charge



On-Resistance vs. Junction Temperature

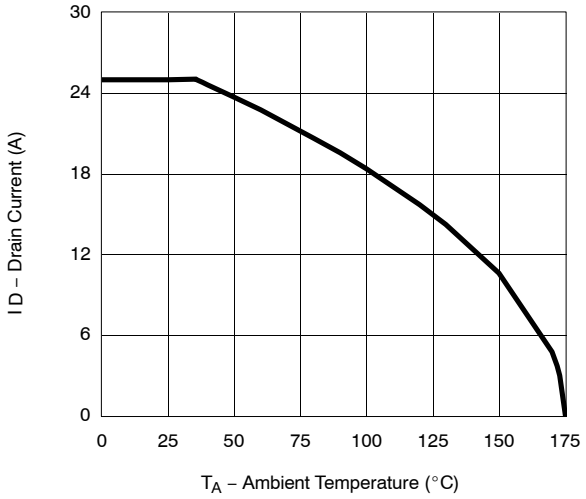


Source-Drain Diode Forward Voltage

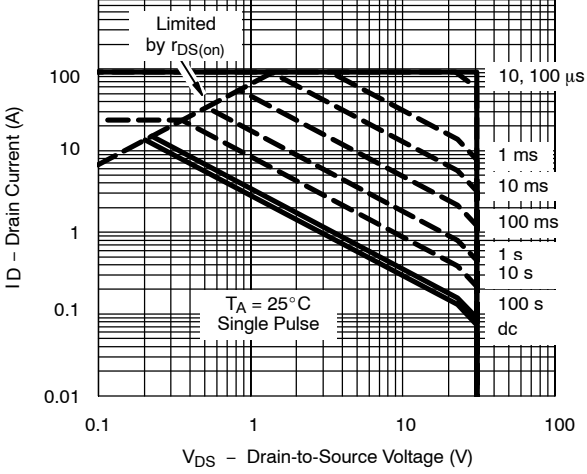


THERMAL RATINGS

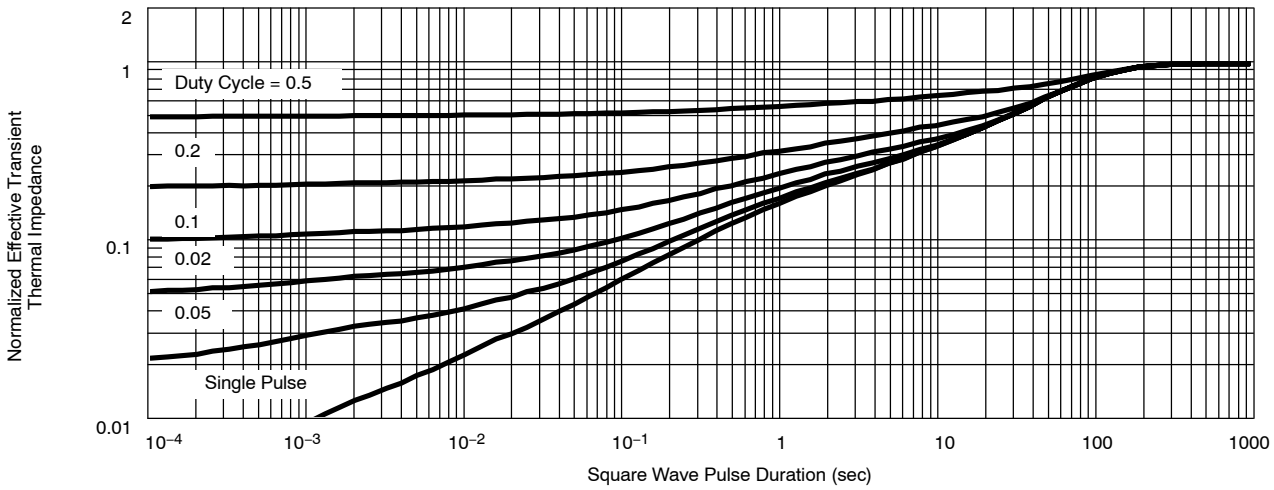
Maximum Drain Current vs. Ambiemt Temperature



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case